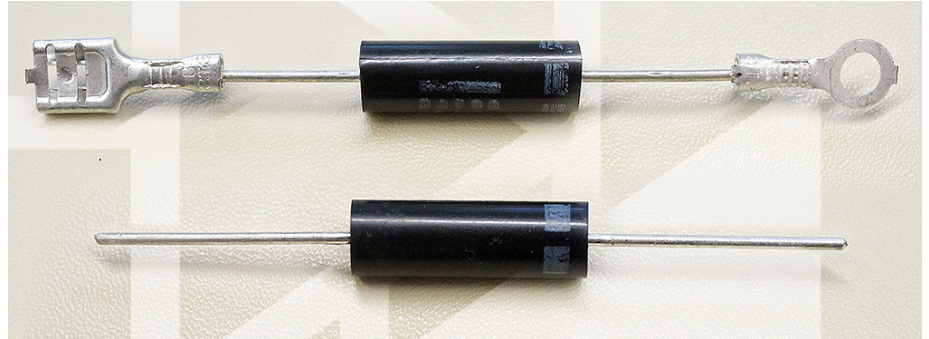




FEATURES

- High Overload Surge Capacity
- Durable Epoxy Resin Package



To order with quick disconnect terminals, use the **partnum-TERM**

ABSOLUTE MAXIMUM RATINGS

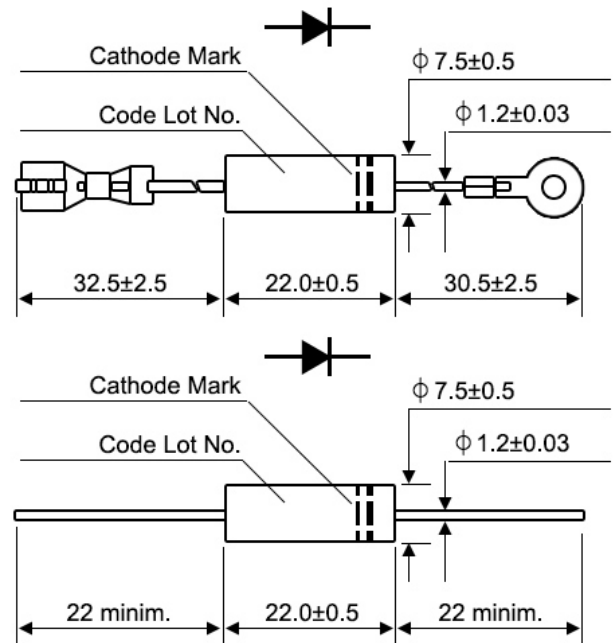
V_{RRM} Repeating Peak Reverse Voltage (kV):	15
T_{JMAX} Max. junction temp.(°C):	130
T_{STG} Storage temp.(°C):	-40 to +130
I_O Avg. Forward Current (mA):	500
I_{FSM} Forward Surge Current (A):	40

ELECTRICAL CHARACTERISTICS

I_{R1} Normal temp. Reverse Current (μA) @ $V_R=V_{RRM}$, $T_{amb}=25^\circ C$:	5.0 max
I_{R2} High temp. Reverse Current (μA) @ $V_R=V_{RRM}$, $T_{amb}=100^\circ C$:	50 max
V_F Forward Voltage Drop (V) @ $I_F=500mA$:	13.0
Reverse Breakdown Voltage (kV) @ $I_R=100\mu A$:	≥ 15

TEST CONDITIONS

High temp. Reverse Voltage @ 1000 hrs.:	$V_{RM}=V_{RRM}$, $f=50Hz$, $T_{AMB}=100^\circ C$ Half sine voltage with $f=50Hz$ applied, $T_{AMB}=100^\circ C$
High temp. storage @ 1000 Hrs.:	$T_{AMB}=130\pm 2^\circ C$
Soldering Resistance Heat Test:	Solder trough temp.: $350\pm 10^\circ C$, Dip Time: $3.5s \pm 0.5s$
High pressure smoke test @ 10 hrs.:	$120^\circ C$, $2 \times 10^5 pa$
Insulation Resistance Test (1000M Ω):	Between the center of the body and terminal (See Fig. 1)
Insulation Strength Test @ 10KV:	1 min. between center of the body and terminal. (Fig.1)
Lead bend test:	Force 10 N to the lead, bent it to pos. and neg. 90°
Lead pull test:	Force 70 N of axial to the lead for 1 min.



Insulation resistance test condition: Measure between A and B by using a DC 500V Insulation resistance tester

Insulation strength test condition: Apply half sine wave voltage with 10kV wave height between A and B in insulation liquid

